IN-MAT TECHNOLOGIES®

TECHNICAL DATA SHEET **Nov’21 Rev 1.6**

IMT-CE06-TM3
ENCAPSULANT EPOXY

IMT-CE06-TM3 is a single component encapsulant epoxy. This product is formulated as a globtop epoxy to protect IC chip for Chip-On-Board and/or Chip-On-Flex applications. It is designed to fast cure at moderate temperature. IMT-CE06-TM3 offers excellent heat and chemical resistance as well as exhibits good adhesion property to PCB and flex-tape.

IMT-CE06-TM3 is non-solvent type and a 100% solid system. It does not contains hazardous, prohibited substances and comply to RoHS3, EU directive 2015/863, Substances of Very High Concern (SVHC) published by ECHA as well as Halogen Free. This product is packed either in syringe or can for automated dispensing.

TYPICAL PROPERTIES*

Cure Conditions	130°C for 30mins 120°C for 60mins
Physical Properties	
Color	Glossy black before & after cure
Consistency	Flowable paste
Specific Gravity	1.46
Viscosity @1rpm, 25˚C	95,000cPs
Thixotropic Index @0.1/1rpm	3.10
Solid Content	100%
Shore D Hardness	92
Glass Transition Temperature, Tg	129.7°C
CTE below Tg (α1)	48.97ppm
CTE above Tg (α2)	138.50ppm
Water Absorption @100°C-1h	< 0.5%wt
Operating Temperature	-40°C to above 150°C
Ionic Contents	
Chloride, Cl-	≤ 650ppm
Bromine, Br-	Not detected
PVC	Not detected
Pot Life	> 4 weeks at room temperature
Shelf Life	18 months at 0°C or below in closed container

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* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.